



Product Description

The SGA3263Z is a high performance SiGe HBT MMIC Amplifier. A Darlington configuration featuring one-micron emitters provides high F_T and excellent thermal performance. The heterojunction increases breakdown voltage and minimizes leakage current between junctions. Cancellation of emitter junction non-linearities results in higher suppression of intermodulation products. Only two DC-blocking capacitors, a bias resistor, and an optional RF choke are required for operation.

Features

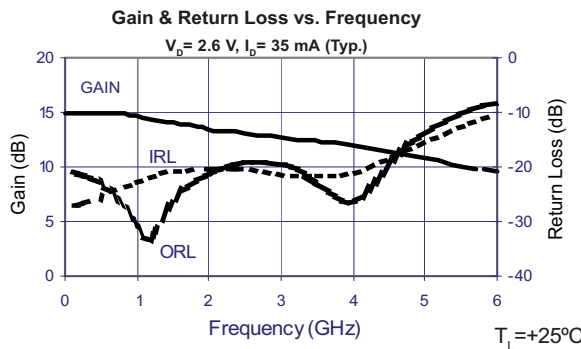
- Broadband Operation: DC to 5500MHz
- Cascadable 50Ω
- Operates from Single Supply
- Low Thermal Resistance Package

Applications

- PA Driver Amplifier
- Cellular, PCS, GSM, UMTS
- IF Amplifier
- Wireless Data, Satellite

Optimum Technology Matching® Applied

- GaAs HBT
- GaAs MESFET
- InGaP HBT
- SiGe BiCMOS
- Si BiCMOS
- SiGe HBT
- GaAs pHEMT
- Si CMOS
- Si BJT
- GaN HEMT
- RF MEMS



Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
Small Signal Gain	13.5	15.0	16.5	dB	850MHz
		13.6		dB	1950MHz
		13.3		dB	2400MHz
Output Power at 1dB Compression		11.6		dBm	850MHz
		10.9		dBm	1950MHz
Output Third Intercept Point		26.2		dBm	850MHz
		24.1		dBm	1950MHz
Bandwidth Determined by Return Loss		5500		MHz	>10dB
Input Return Loss		20.3		dB	1950MHz
Output Return Loss		21.5		dB	1950MHz
Noise Figure		3.8		dB	1950MHz
Device Operating Voltage	2.3	2.6	2.9	V	
Device Operating Current	31	35	39	mA	
Thermal Resistance (Junction - Lead)		255		°C/W	

Test Conditions: $V_S=5V$, $I_D=35mA$ Typ., OIP₃ Tone Spacing = 1MHz, P_{OUT} per tone = -5dBm, R_{BIAS} = 68Ω, T_L = 25°C, Z_S = Z_L = 50Ω

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Current (I_D)	70	mA
Max Device Voltage (V_D)	4	V
Max RF Input Power	+18	dBm
Max Junction Temp (T_J)	+150	°C
Operating Temp Range (T_L)	-40 to +85	°C
Max Storage Temp	+150	°C

Operation of this device beyond any one of these limits may cause permanent damage. For reliable continuous operation, the device voltage and current must not exceed the maximum operating values specified in the table on page one.

Bias Conditions should also satisfy the following expression:

$$I_D V_D < (T_J - T_L) / R_{TH, J-I}$$



Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

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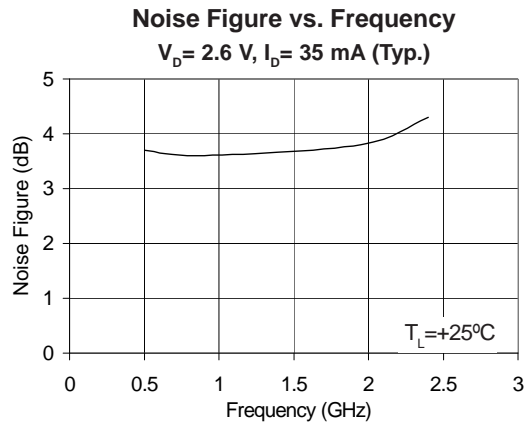
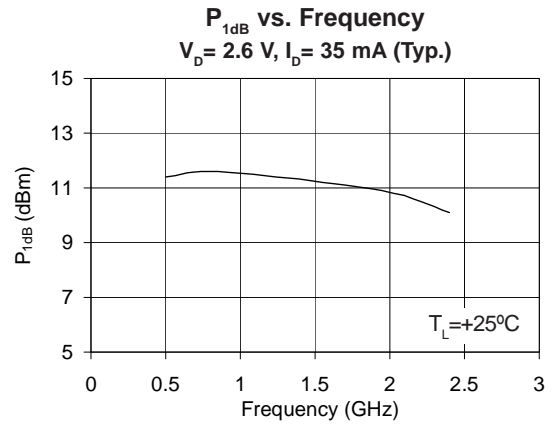
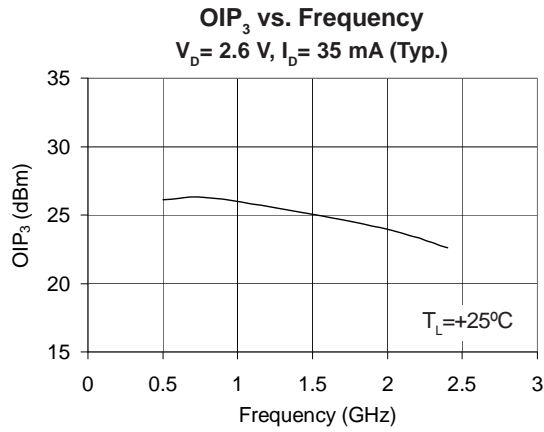


RFMD Green: RoHS compliant per EU Directive 2002/95/EC, halogen free per IEC 61249-2-21, < 1000ppm each of antimony trioxide in polymeric materials and red phosphorus as a flame retardant, and <2% antimony in solder.

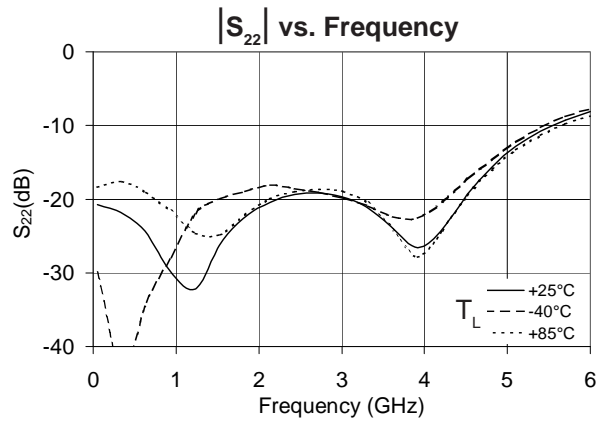
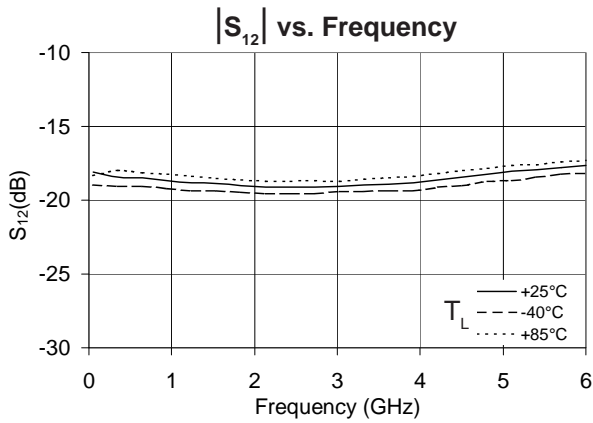
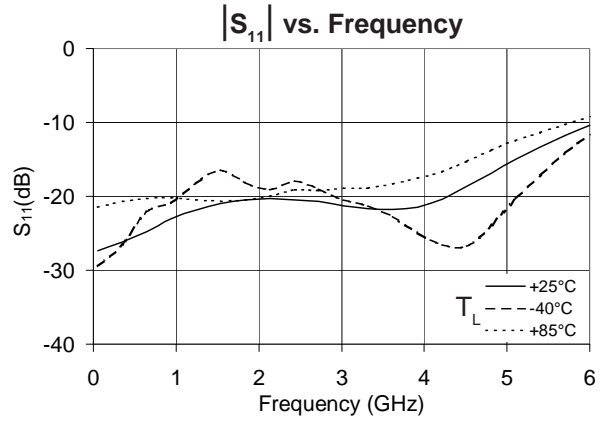
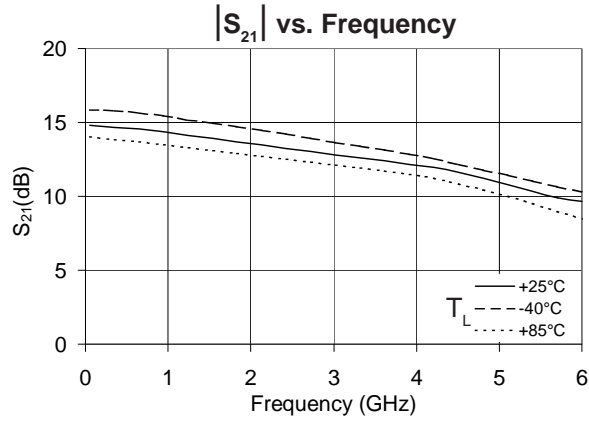
Typical Performance at Key Operating Frequencies

Parameter	Unit	100 MHz	500 MHz	850 MHz	1950 MHz	2400 MHz	3500 MHz
Small Signal Gain	dB	15.4	15.2	15.0	13.6	13.3	12.5
Output Third Order Intercept Point	dBm		26.1	26.2	24.1	22.6	
Output Power at 1dB Compression	dBm		11.4	11.6	10.9	10.1	
Input Return Loss	dB	27.0	25.6	23.6	20.3	20.4	21.8
Output Return Loss	dB	20.8	22.9	28.0	21.5	19.4	22.7
Reverse Isolation	dB	18.2	18.4	18.6	19.1	19.1	18.9
Noise Figure	dB		3.7	3.6	3.8	4.3	

Test Conditions: $V_S = 5V$, $I_D = 35mA$ Typ., OIP₃ Tone Spacing = 1MHz, P_{OUT} per tone = -5dBm, R_{BIAS} = 68Ω, T_L = 25°C, Z_S = Z_L = 50Ω

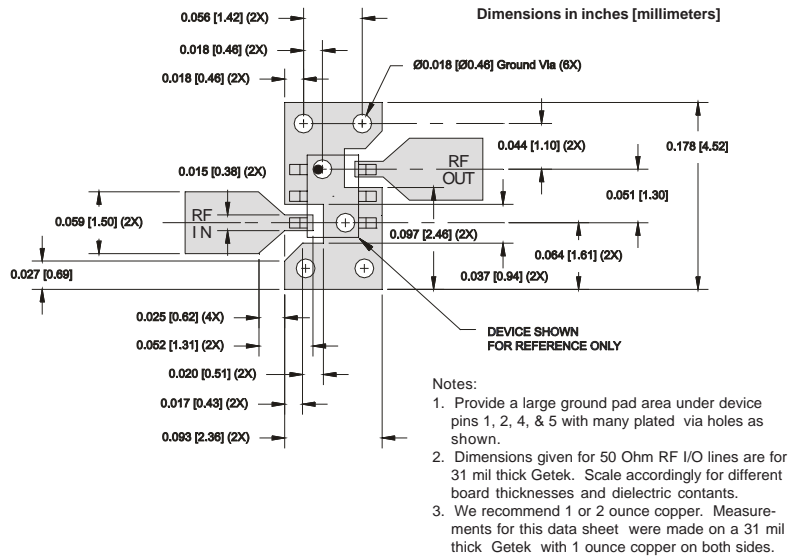


Typical RF Performance Over Temperature (Bias: $V_D=2.6V$, $I_D=35mA$)



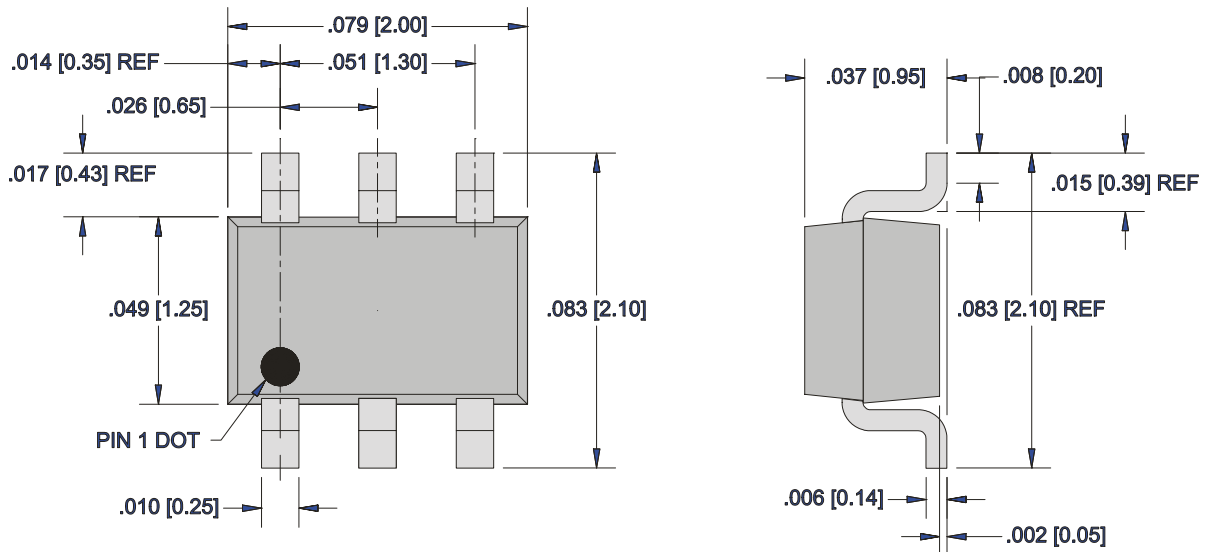
Pin	Function	Description
3	RF IN	RF input pin. This pin requires the use of an external DC-blocking capacitor chosen for the frequency of operation.
1, 2, 4, 5	GND	Connection to ground. For optimum RF performance, use via holes as close to ground leads as possible to reduce lead inductance.
6	RF OUT/BIAS	RF output and bias pin. DC voltage is present on this pin, therefore a DC-blocking capacitor is necessary for proper operation.

Suggested Pad Layout

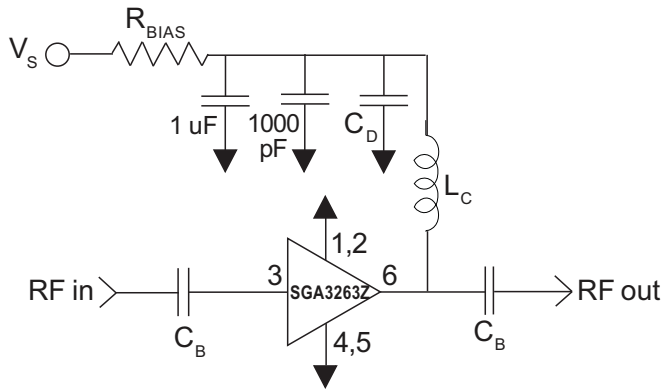


Package Drawing

Dimensions in inches (millimeters)
Refer to drawing posted at www.rfmd.com for tolerances.



Application Schematic

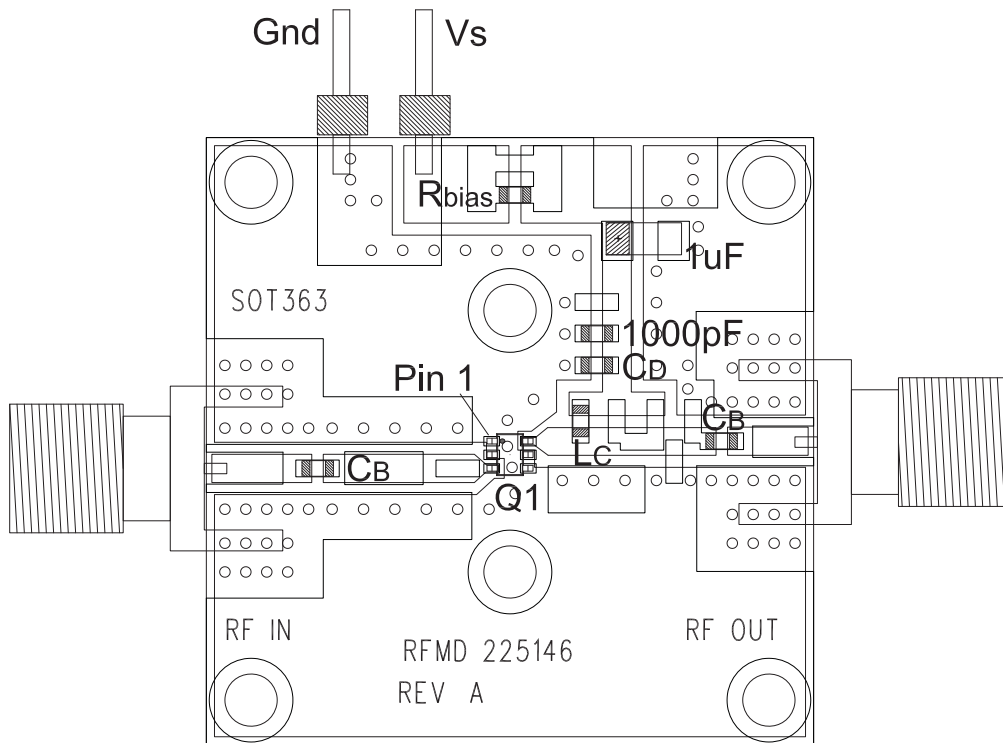


Reference Designator	Frequency (Mhz)				
	500	850	1950	2400	3500
C _B	220 pF	100 pF	68 pF	56 pF	39 pF
C _D	100 pF	68 pF	22 pF	22 pF	15 pF
L _C	68 nH	33 nH	22 nH	18 nH	15 nH

Recommended Bias Resistor Values for I _b =35mA				
$R_{BIAS} = (V_S - V_D) / I_D$				
Supply Voltage (V _S)	5 V	8 V	10 V	12 V
R _{BIAS}	68 Ω	150 Ω	200 Ω	270 Ω

Note: R_{BIAS} provides DC bias stability over temperature.

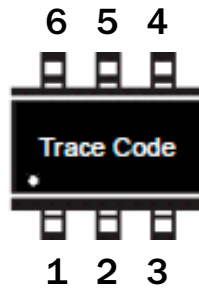
Evaluation Board Layout



Mounting Instructions:

1. Use a large droung pad area near device pins 1, 2, 4, and 5 with plated through-holes as shown.
2. We recommend 1 or 2 ounces copper. Measurements for this data sheet were made on a 31mil thick FR-4 board with 1 ounce copper on both sides.

Part Identification



Ordering Information

Ordering Code	Description
SGA3263Z	7" Reel with 3000 pieces
SGA3263ZSQ	Sample bag with 25 pieces
SGA3263ZSR	7" Reel with 100 pieces
SGA3263ZPCK1	850MHz, 5V Operation PCBA with 5-piece sample bag